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(54) Title: BOTTOM CLIPPED STUD-SOCKET ASSEMBLIES FOR DIELECTRIC ETCH CHAMBER ELECTRODES

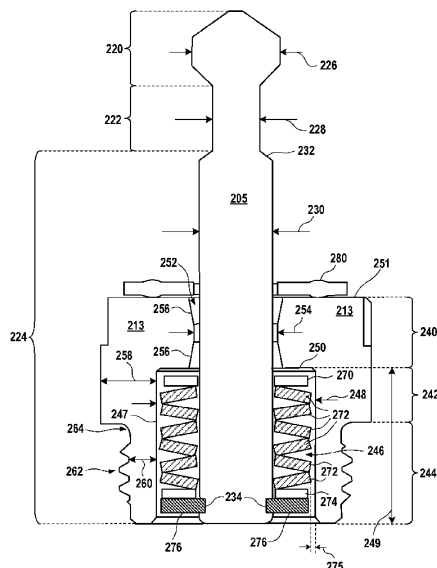


FIG. 3

(57) Abstract: A stud-socket assembly includes: a stud pin having a head portion, a main body, and a neck portion that connects the head portion to the main body; a socket having a cylindrical interior volume, and having an upper opening through which the stud pin is disposed, the upper opening having an inner diameter that is less than the outer diameter of the head portion of the stud pin by at least 0.005 inch; a plurality of Belleville washers that circumferentially surround the main body of the stud pin; a retainer attached to the second end of the main body of the stud pin, the retainer configured to retain the plurality of Belleville washers within the cylindrical interior volume of the socket.

WO 2025/111097 A1